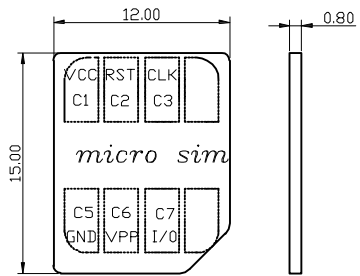
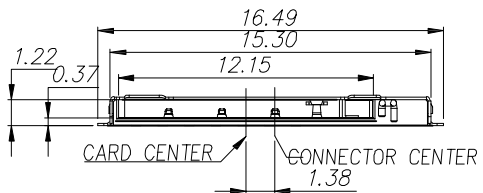
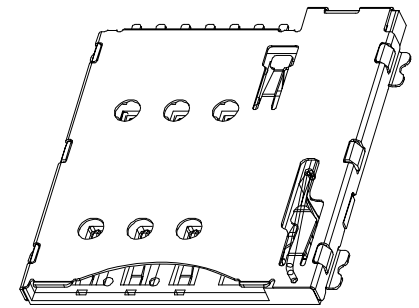
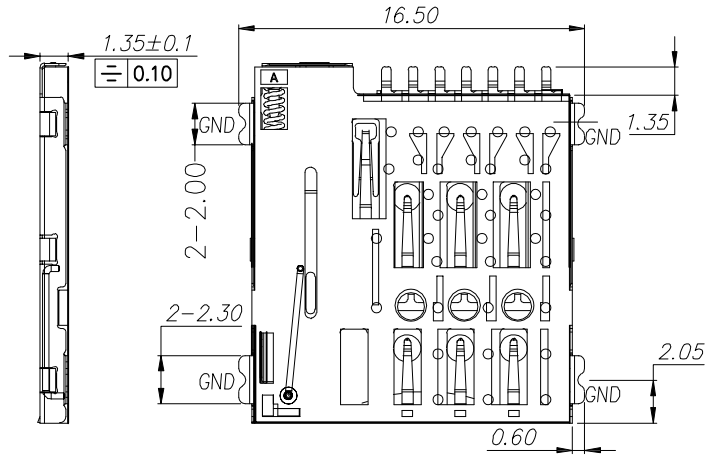
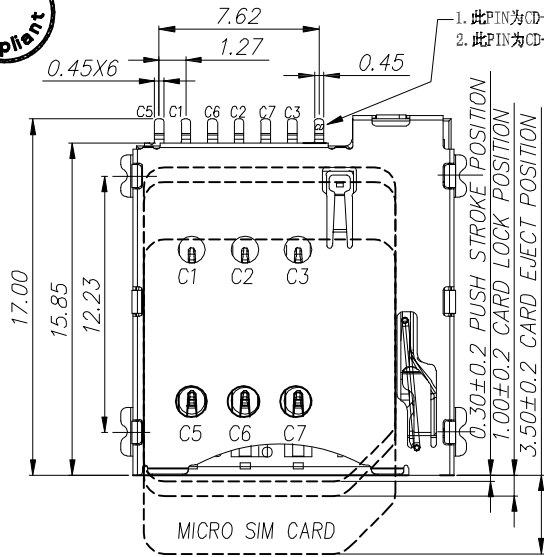
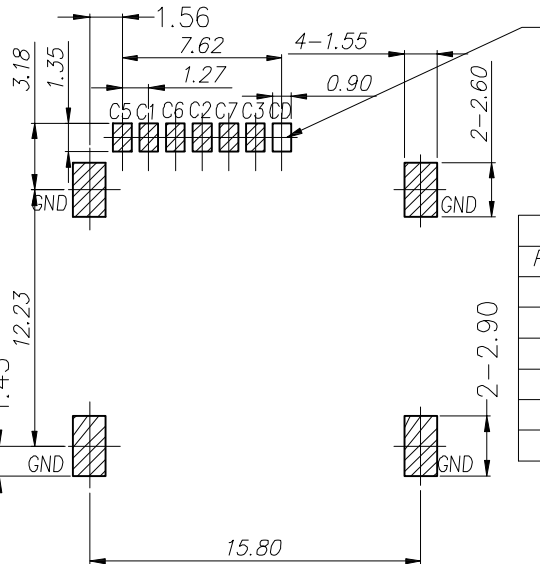


DATE	DR.BY	ECN.NO.	DESCRIPTION	MARK	VER.
5/30'16			NEW DWG		A0



MICRO SIM CARD



SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

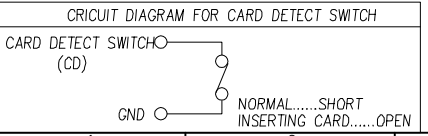
Specification

MATERIAL:
 Insulator: High Temperature Thermoplastic, UL 94V-0.
 Contact: Copper Alloy
 Shell: STAINLESS

PLATING:
 Contact: Plated 50u'' Ni Overall Contact Au 1U
 Shell: Plated 50u'' Ni Overall
 Plated 1u''Au Selective Contact Area

Electrical:
 Current Rating :0.5mA AC/DC max.
 Voltage Rating :125V AC/DC
 Ambient Temperature Range :-20° C~+60° C
 Storage Temperature Range :40° C~+70° C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩmax.
 Insulation Resistance:1000Ωmin./500VDC
 Mating Cycles:5,000 Insertions
 产品耐温温度: 260° C ±5°

■ CIRCUIT TRACE KEEP OUT AREA
 ■ SMT SOLDER AREA
 THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.
 RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05



-TOLERANCES- UNLESS OTHERWISE SPECIFIED 公差参考表				东莞市龙科电子科技有限公司 DONGGUAN LONGKE ELECTRONICS CO.,LTD :				
				APPD: 核准: 邹重庆 CHECK: dd 校对: 范小飞 DRAW: 绘图: 何俊勇		TITLE: Micro-SIM 卡座PUSH 产品品名: 6PIN 1.3H 带CD PIN PRODUCT NO: 197-F0636230-B25 产品料号:		
X.X	±0.25	X.X*	±3.0°	DATE	SCALE	UNIT	TYPE	PAGE
X.XX	±0.20	X.XX*	±1.0°	2016.05.30	1:1	mm	CD	1/1
X.XXX	±0.10	X.XXX*	±0.500°					

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